





TEXAS INSTRUMENTS

TXU0104 SCES937A – MAY 2021 – REVISED SEPTEMBER 2021

TXU0104 4-Bit Fixed Direction Voltage-Level Translator with Schmitt-Trigger Inputs and 3-State Outputs

1 Features

- Fully configurable dual-rail design allows each port to operate from 1.1 V to 5.5 V
- Up to 200 Mbps support for 3.3 V to 5.0 V
- Schmitt-trigger inputs allows for slow and noisy inputs
- Inputs with integrated static pull-down resistors
 prevent channels from floating
- High drive strength (up to 12 mA at 5 V)
- Low power consumption
 - 2.5 μA maximum (25°C)
 - 6 μA maximum (–40°C to 125°C)
- V_{CC} isolation and V_{CC} disconnect (I_{off-float}) feature
 - If either V_{CC} input is <100 mV or disconnected, all outputs are disabled and become highimpedance
- I_{off} supports partial-power-down mode operation
- Control logic (OE) with V_{CC(MIN)} circuitry allows for control from either A or B port
- Pinout compatible with TXB family level shifters
- Available in other variants that support common applications: TXU0204, TXU0304
- Operating temperature from –40°C to +125°C
- Latch-up performance exceeds 100 mA per JESD 78, class II
- ESD protection exceeds JESD 22
 - 2500-V human-body model
 - 1500-V charged-device model

2 Applications

- · Eliminate slow or noisy input signals
- Driving indicator LEDs or buzzers
- Debouncing a mechanical switch
- General purpose I/O level shifting
- Push-pull level shifting (UART, SPI, JTAG, and so forth)

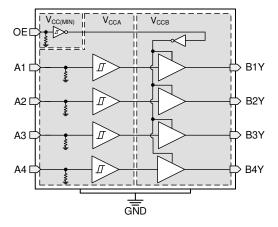
3 Description

TXU0104 is a 4-bit, dual-supply noninverting fixed direction voltage level translation device. Ax pins are referenced to V_{CCA} logic level, OE pin can be referenced to either V_{CCA} or V_{CCB} logic levels, and Bx pins are referenced to V_{CCB} logic levels. The A port is able to accept input voltages ranging from 1.1 V to 5.5 V, while the B port can also accept input voltages from 1.1 V to 5.5 V. Fixed direction data transmission can occur from A to B or B to A when OE is set to high in reference to either supply. When OE is set to low, all output pins are in the high-impedance state. See *Device Functional Modes* for a summary of the operation of the control logic.

Device Information⁽¹⁾

PART NUMBER	PACKAGE	BODY SIZE (NOM)				
TXU0104BQA	VQFN (14)	3.00 mm × 2.50 mm				
TXU0104PW	TSSOP (14)	5.00 mm × 4.40 mm				
TXU0104RUT	UQFN (12)	2.00 mm × 1.70 mm				
TXU0104DTR	X2SON (12)	1.70 mm × 1.00 mm				

(1) For all available packages, see the orderable addendum at the end of the data sheet.



TXU0104 Functional Block Diagram



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4 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

C	hanges from Revision * (May 2021) to Revision A (September 2021)	Page
•	Changed the status of the TXU0104BQA, TXU0104RUT, and TXU0104DTR devices from: Product Prev	view
	to: Production Data	1



5 Related Products

TXU0x04 4-Bit
Unidirectional
Voltage-Level
TranslatorsTXU0x04 are 4-bit, dual-supply noninverting fixed direction voltage level translators. These
devices are compatible to the TXB0104 with the same pinout allowing for a drop in
replacement. The OE pin can be referenced to either V_{CCA} or V_{CCB} logic levels allowing
for one of the TXU0x04 devices to be used for fixed direction, high drive applications which
the TXB0104 is not recommended to support.

TXU0204

TXU0204 is a 4-bit, dual-supply noninverting fixed direction voltage level translators with 2 channels in the opposing direction commonly used for GPIO, UART, and JTAG translation.

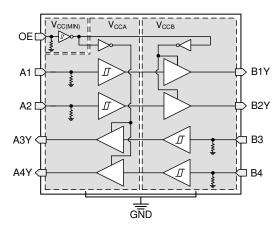


Figure 5-1. TXU0204 Functional Block Diagram

TXU0304 TXU0304 is a 4-bit, dual-supply noninverting fixed direction voltage level translators with 1 channel in the opposing direction commonly used for GPIO, SPI, and I2S translation.

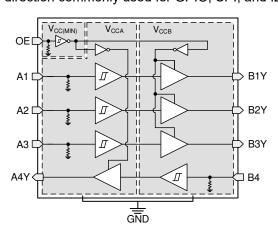


Figure 5-2. TXU0304 Functional Block Diagram

6 Pin Configuration and Functions—TXU0104

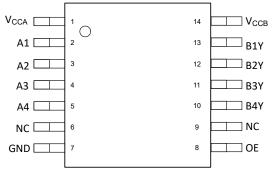


Figure 6-1. PW 14-Pin TSSOP Top View

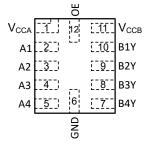


Figure 6-3. RUT Package 12-Pin UQFN Transparent Top View

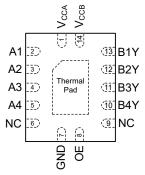


Figure 6-2. BQA Package 14-Pin VQFN Transparent Top View

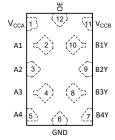


Figure 6-4. DTR Package 12-Pin X2SON Transparent Top View

	PIN		I/O	DESCRIPTION					
Name	PW, BQA	RUT, DTR		DESCRIPTION					
A1	2	2	I	Input A1. Referenced to V _{CCA} .					
A2	3	3	I	Input A2. Referenced to V _{CCA} .					
A3	4	4	I	Input A3. Referenced to V _{CCA} .					
A4	5	5	I	Input A4. Referenced to V _{CCA} .					
B1Y	13	10	0	Output B1. Referenced to V _{CCB} .					
B2Y	12	9	0	O Output B2. Referenced to V _{CCB} .					
B3Y	11	8	0	Output B3. Referenced to V _{CCB} .					
B4Y	10	7	0	Output B4. Referenced to V _{CCB} .					
GND	7	6	_	Ground					
NC	6, 9		_	No internal connection.					
OE	8	12	I	Output Enable. Pull to GND to place all outputs in high-impedance mode. Pull to V_{CCA} or V_{CCB} to enable all outputs.					
V _{CCA}	1	1	_	A-port supply voltage. 1.1 V \leq V _{CCA} \leq 5.5 V					
V _{CCB}	14	11	_	B-port supply voltage. 1.1 V \leq V _{CCB} \leq 5.5 V					
PAD	_		_	Thermal pad. May be grounded (recommended) or left floating.					

Table 6-1. TXU0104 Pin Functions



7 Specifications

7.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

			MIN	MAX	UNIT
V _{CCA}	Supply voltage A		-0.5	6.5	V
V _{CCB}	Supply voltage B		-0.5	6.5	V
		I/O Ports (A Port)	-0.5	6.5	
VI	Input Voltage ⁽²⁾	I/O Ports (B Port)	-0.5	6.5	V
		OE	-0.5	6.5	
V	Voltage applied to any output in the high-impedance or power-off	A Port	-0.5	6.5	V
	state ⁽²⁾	B Port	-0.5	6.5	v
V	Voltage applied to any output in the high or low state ^{(2) (3)}	A Port	-0.5	V _{CCA} + 0.5	V
Vo		B Port	-0.5	V _{CCB} + 0.5	v
I _{IK}	Input clamp current	V ₁ < 0	-20		mA
I _{OK}	Output clamp current	V _O < 0	-20		mA
I _O	Continuous output current	·	-25	25	mA
	Continuous current through V _{CC} or GND		-100	100	mA
Tj	Junction Temperature		150	°C	
T _{stg}	Storage temperature		-65	150	°C

(1) Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under Recommended Operating Conditions. Exposure beyond the limits listed in Recommended Operating Conditions. may affect device reliability.

(2) The input voltage and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.

(3) The output positive-voltage rating may be exceeded up to 6.5 V maximum if the output current rating is observed.

7.2 ESD Ratings

			VALUE	UNIT
V	Electrostatic discharge	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001 ⁽¹⁾	±2500	V
V _(ESD)		Charged device model (CDM), per JEDEC specification JESD22-C101 ⁽²⁾	±1500	V

(1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.

(2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.



7.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted) (1) (2) (3)

				MIN	MAX	UNIT
V _{CCA}	Supply voltage A			1.08	5.5	V
V _{CCB}	Supply voltage B			1.08	5.5	V
			V _{CCO} = 1.1 V		-1.5	
			V _{CCO} = 1.4 V		-3	
1	High-level output o	urront	V _{CCO} = 1.65 V		-4.5	m۸
I _{OH}		unent	V _{CCO} = 2.3 V		-8	mA
			V _{CCO} = 3 V	-10		
			V _{CCO} = 4.5 V		-12	
			V _{CCO} = 1.1 V		1.5	
			V _{CCO} = 1.4 V		3	
		urrant	V _{CCO} = 1.65 V		4.5	mA
I _{OL}	Low-level output c	urrent	V _{CCO} = 2.3 V		8	mA
			V _{CCO} = 3 V		10	
			V _{CCO} = 4.5 V		12	
VI	Input voltage ⁽³⁾		·	0	5.5	V
V	Output voltage	Active State		0	V _{CCO}	V
Vo	Output voltage	Tri-State		0	5.5	V
T _A	Operating free-air	temperature		-40	125	°C

(1) V_{CCI} is the V_{CC} associated with the input port.

(2) V_{CCO} is the V_{CC} associated with the output port.

(3) All control inputs and data I/Os of this device have weak pulldowns to ensure the line is not floating when undefined external to the device. The input leakage from these weak pulldowns is defined by the I_I specification indicated under Electrical Characteristics.

7.4 Thermal Information

			٦	TXU0104		
	THERMAL METRIC ⁽¹⁾	PW (TSSOP)	BQA (WQFN)	RUT (UQFN)	DTR (X2SON)	UNIT
		14 PINS	14 PINS	12 PINS	12 PINS	
R _{θJA}	Junction-to-ambient thermal resistance	135.8	87.2	171.9	176.6	°C/W
R _{0JC(top)}	Junction-to-case (top) thermal resistance	65.0	90.0	100.4	84.1	°C/W
R _{θJB}	Junction-to-board thermal resistance	78.8	56.0	97.1	99.1	°C/W
Y _{JT}	Junction-to-top characterization parameter	15.6	9.8	10.9	2.6	°C/W
Y _{JB}	Junction-to-board characterization parameter	78.2	56.0	95.5	98.9	°C/W
R _{0JC(bottom)}	Junction-to-case (bottom) thermal resistance	N/A	33.0	N/A	N/A	°C/W

(1) For more information about traditional and new thermal metrics, see the Semiconductor and IC Package Thermal Metrics application report.



7.5 Electrical Characteristics

over operating free-air temperature range (unless otherwise noted)^{(1) (2)}

				Operating free-air temperature (T _A)		۵)						
PARAMETER		TEST CONDITIONS	V _{CCA}	V _{CCB}	25°C			–40°	C to 85°C	-40°	UN	
					MIN	TYP	MAX	MIN	TYP MAX	MIN	TYP MA	K
			1.1 V	1.1 V				0.44	0.88	0.44	0.8	8
			1.4 V	1.4 V				0.60	0.98	0.60	0.9	В
		Data Inputs	1.65 V	1.65 V				0.76	1.13	0.76	1.1	3
		(Ax, Bx)	2.3 V	2.3 V				1.08	1.56	1.08	1.5	6 V
		(Referenced to V _{CCI})	3 V	3 V				1.48	1.92	1.48	1.9	2
	Positive-		4.5 V	4.5 V				2.19	2.74	2.19	2.7	4
V _{T+}	going input-		5.5 V	5.5 V				2.65	3.33	2.65	3.3	3
v T+	threshold		1.1 V	1.1 V				0.44	0.88	0.44	0.8	В
	voltage		1.4 V	1.4 V				0.60	0.98	0.60	0.9	В
		OE	1.65 V	1.65 V				0.76	1.13	0.76	1.1	3
		(Referenced to V _{CCA}	2.3 V	2.3 V				1.08	1.56	1.08	1.5	6 V
		or V_{CCB}	3 V	3 V				1.48	1.92	1.48	1.9	2
			4.5 V	4.5 V				2.19	2.74	2.19	2.7	4
		5.5 V	5.5 V				2.65	3.33	2.65	3.3	3	
		1.1 V	1.1 V				0.17	0.48	0.17	0.4	8	
		1.4 V	1.4 V				0.28	0.59	0.28	0.5	9	
		Data Inputs (Ax, Bx) (Referenced to V _{CCI})	1.65 V	1.65 V				0.35	0.69	0.35	0.6	9
			2.3 V	2.3 V				0.56	0.97	0.56	0.9	7 V
			3 V	3 V				0.89	1.5	0.89	1.	5
	Nevetive		4.5 V	4.5 V				1.51	1.97	1.51	1.9	7
	Negative- going input-		5.5 V	5.5 V				1.88	2.4	1.88	2.	4
V _{T-}	threshold		1.1 V	1.1 V				0.17	0.48	0.17	0.4	8
	voltage	OE (Referenced to V_{CCA} or V_{CCB})	1.4 V	1.4 V				0.28	0.59	0.28	0.5	9
			1.65 V	1.65 V				0.35	0.69	0.35	0.6	9
			2.3 V	2.3 V				0.56	0.97	0.56	0.9	7 V
			3 V	3 V				0.89	1.5	0.89	1.	5
			4.5 V	4.5 V				1.51	1.97	1.51	1.9	7
			5.5 V	5.5 V	-			1.88	2.46	1.88	2.4	6
			1.1 V	1.1 V				0.2	0.4	0.2	0.	4
			1.4 V	1.4 V				0.25	0.5	0.25	0.	5
		Data Inputs	1.65 V	1.65 V	-			0.3	0.55	0.3	0.5	5
		(Ax, Bx)	2.3 V	2.3 V				0.38	0.65	0.38	0.6	5 V
		(Referenced to V_{CCI})	3 V	3 V	-			0.46	0.72	0.46	0.7	2
			4.5 V	4.5 V				0.58	0.93	0.58	0.9	3
	Input- threshold		5.5 V	5.5 V				0.69	1.06	0.69	1.0	6
ΔV _T	hysteresis		1.1 V	1.1 V				0.15	0.41	0.15	0.4	1
	$(V_{T^+} - V_{T^-})$		1.4 V	1.4 V	+			0.2	0.5	0.2	0.	_
		OE	1.65 V	1.65 V	+			0.23	0.55	0.23	0.5	5
		(Referenced to V _{CCA}	2.3 V	2.3 V	+			0.32	0.65	0.32	0.6	-
		or V _{CCB)}	3 V	3 V	+			0.39	0.72	0.39	0.7	-
			4.5 V	4.5 V				0.57	0.97	0.57	0.9	_
			5.5 V	5.5 V				0.69	1.18	0.69	1.1	-

7.5 Electrical Characteristics (continued)

over operating free-air temperature range (unless otherwise noted)^{(1) (2)}

						Operating free-air temperature (T _A)						
PA	RAMETER	TEST CONDITIONS	V _{CCA}	V _{CCB}		25°C		-40 °	C to 85°C	-40 °	C to 125°C	UNI
					MIN	TYP	MAX	MIN	TYP MA	X MIN	TYP MAX	
		I _{OH} = -0.1 mA	1.1V – 5.5V	1.1V – 5.5V				V _{CCO} - 0.1		V _{CCO} - 0.1		
		I _{OH} = -0.5 mA	1.1 V	1.1 V				0.82		0.82		
.,	High-level	I _{OH} = -3 mA	1.4 V	1.4 V				1		1].
V _{OH}	output voltage ⁽³⁾	I _{OH} = -4.5 mA	1.65 V	1.65 V				1.2		1.2		V
		I _{OH} =8 mA	2.3 V	2.3 V				1.7	·	1.7		
		I _{OH} = -10 mA	3 V	3 V				2.2		2.2		
		I _{OH} = -12 mA	4.5 V	4.5 V				3.7		3.7		
		I _{OL} = 0.1 mA	1.1V – 5.5V	1.1V – 5.5V					0.	1	0.1	
		I _{OL} = 0.5 mA	1.1 V	1.1 V					0.2	7	0.27	1
		I _{OL} = 3 mA	1.4 V	1.4 V					0.3	5	0.35	
. /	Low-level	I _{OL} = 4.5 mA	1.65 V	1.65 V					0.4	5	0.45	Ι.
V _{OL}	output voltage ⁽⁴⁾	I _{OL} = 8 mA	2.3 V	2.3 V					0.	7	0.7	
	5	I _{OL} = 10 mA	3 V	3 V					0.	8	0.8	1
		I _{OL} = 8 mA	4.5 V	4.5 V					0.5	5	0.55	
		I _{OL} = 12 mA	4.5 V	4.5 V					0.	8	0.8	
Input leaka current		OE V _I = V _{CC} or GND	1.1V – 5.5V	1.1V – 5.5V	-0.1		1.5	-0.1	1.	5 -0.1	2	μ
	Input leakage current	Data Inputs (Ax, Bx) V _I = V _{CCI} or GND	1.1V – 5.5V	1.1V – 5.5V	-0.1		1.5	-0.1	1.	5 –2	2	μ
	Partial power	A Port or B Port	0 V	0 V - 5.5 V	-1.5		1.5	-2		2 –2.5	2.5	
l _{off}		V _I or V _O = 0 V - 5.5 V	0 V - 5.5 V	0 V	-1.5		1.5	-2		2 –2.5	2.5	μ
	Floating		Floating ⁽⁵⁾	0 V - 5.5 V	-1.5		1.5	-2		2 –2.5	2.5	
I _{off-float}	supply Partial power down current	A Port or B Port V _I or V _O = GND	0 V - 5.5 V	Floating ⁽⁵⁾	-1.5		1.5	-2		2 –2.5	2.5	μ
I _{OZ}	Tri-state output current	A or B Port: $V_1 = V_{CC1}$ or GND $V_0 = V_{CC0}$ or GND OE = GND	1.1V – 5.5V	1.1V – 5.5V	-0.3		0.3	-1		1 –2	2	μ
			1.1V – 5.5V	1.1V – 5.5V			1.5		2.	5	6	
	V _{CCA} supply	$V_I = V_{CCI}$ or GND $I_O = 0$	0 V	5.5 V	-0.3			-1		-1		
I _{CCA}	current		5.5 V	0 V			1		1.	5	3	μ
		$V_{I} = GND$ $I_{O} = 0$	5.5 V	Floating ⁽⁵⁾			1.5			7	15	
			1.1V – 5.5V	1.1V – 5.5V			1.5		2.	5	6	
		$V_I = V_{CCI}$ or GND $I_O = 0$	0 V	5.5 V			1		1.	5	3	
I _{CCB}	V _{CCB} supply current	10 - 0	5.5 V	0 V	-0.3			-1		-1		μ
		$V_1 = GND$ $I_0 = 0$	Floating ⁽⁵⁾	5.5 V			1.5			7	15	
I _{CCA} + I _{CCB}	Combined supply current	$V_{I} = V_{CCI}$ or GND $I_{O} = 0$	1.1V – 5.5V	1.1V – 5.5V			2.5			3	6	μ
Ci	Control Input Capacitance	V _I = 3.3 V or GND	3.3 V	3.3 V		2.75			3		3.5	р



7.5 Electrical Characteristics (continued)

over operating free-air temperature range (unless otherwise noted)⁽¹⁾ (2)

PARAMETER		TEST CONDITIONS		V _{CCB}	Operating free-air temperature (T _A)									
			V _{CCA}		25°C		–40°C to 85°C			–40°C to 125°C		UNIT		
	MIN				TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX		
C _{io}	Data I/O Capacitance	OE = GND, V _O = 1.65V DC +1 MHz -16 dBm sine wave	3.3 V	3.3 V		3			4			4		pF

(1) V_{CCI} is the V_{CC} associated with the input port

(2) V_{CCO} is the V_{CC} associated with the output port

(2) V(2) is the V(2) according that the current part of the vector part of the v

7.6 Switching Characteristics: T_{sk}, T_{MAX}

over operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CON		V _{cci}	V _{cco}	Opera tempo	UNIT		
		Difference		•000		C to 12	-	UNIT
		1			MIN	TYP	MAX	
			3.0 V - 3.6 V	4.5 V - 5.5 V	200			
			1.65 V - 1.95 V	4.5 V - 5.5 V	150			
		Up Translation	1.1 V - 1.3 V	4.5 V - 5.5 V	30			
T _{MAX} - Maximum Data Rate	50% Duty Cycle		1.65 V - 1.95 V	3.0 V - 3.6 V	100			
	Input One channel		1.1 V - 1.3 V	3.0 V - 3.6 V	30			
	switching		1.1 V - 1.3 V	1.65 V - 1.95 V	20			Mbps
	20% of pulse >		4.5 V - 5.5 V	3.0 V - 3.6 V	125			wiphs
	0.7*V _{CCO} 20% of pulse <		4.5 V - 5.5 V	1.65 V - 1.95 V	50			
	0.3*V _{CCO}	Down Translation	4.5 V - 5.5 V	1.1 V - 1.3 V	10			
			3.0 V - 3.6 V	1.65 V - 1.95 V	50			
			3.0 V - 3.6 V	1.1 V - 1.3 V	10			
			1.65 V - 1.95 V	1.1 V - 1.3 V	10			
			3.0 V - 3.6 V	4.5 V - 5.5 V			3	
			1.65 V - 1.95 V	4.5 V - 5.5 V			10	
		Lin Translation	1.1 V - 1.3 V	4.5 V - 5.5 V			42	
		Up Translation	1.65 V - 1.95 V	3.0 V - 3.6 V			8	
	Timing skew		1.1 V - 1.3 V	3.0 V - 3.6 V			42	
	between any		1.1 V - 1.3 V	1.65 V - 1.95 V			45	
t _{sk} - Output skew	switching outputs on the rising or falling		4.5 V - 5.5 V	3.0 V - 3.6 V			3	ns
	edge		4.5 V - 5.5 V	1.65 V - 1.95 V			10	
			4.5 V - 5.5 V	1.1 V - 1.3 V			42	
			3.0 V - 3.6 V	1.65 V - 1.95 V			8	
			3.0 V - 3.6 V	1.1 V - 1.3 V			42	
			1.65 V - 1.95 V	1.1 V - 1.3 V			45	



7.7 Switching Characteristics, $V_{CCA} = 1.2 \pm 0.1 V$

				_						B-Port	Supply	Voltag	ge (V _{CCB})							
	PARAMETER	FROM	то	Test Conditions	1.2 ± 0.1	I V	1.5	± 0.1 V		1.8 ± 0.	15 V	2.	.5 ± 0.2 V		3.3	3 ± 0.3 V		5.0 ± 0.5	5 V	UNIT
					MIN TYP	MAX	MIN	TYP MA	хм	ΙΝ ΤΥΡ	MAX	MIN	TYP M	٩X	MIN	TYP MA	X MIN	TYP	MAX	
		А	в	-40°C to 85°C	3.3	96	0.5		13 C	.5	37	0.5		32	0.5	3	0 0.5	;	31	
	Propagation	^		-40°C to 125°C	5.7	60	3.0		89 1	.4	33	0.5		28	0.5	2	7 0.5	5	26	ns
t _{pd}	delay	В	A	-40°C to 85°C	3.3	95	1.9		30 C	.5	75	0.5		70	0.5	6	9 0.5	5	69	
		Б	A	-40°C to 125°C	5.7	60	4.1		51 2	.9	48	1.8		45	1.5	4	4 1.3	5	44	
		OE	A	-40°C to 85°C	28.8	133	28.5	1	80 28	.4	133	28.8	1	37	28.4	14	3 18.7	,	211	
+	Disable time	OL		-40°C to 125°C	43.3	133	43.3	1	80 43	.7	130	44.7	1	31	45.4	13	4 31.8	;	140	ns
t _{dis}		OE	В	-40°C to 85°C	32.5	150	27.6	1	7 25	.8	110	22.5	1	04	22.1	11	2 20.1		181	115
		0E	D	-40°C to 125°C	48.3	149	43.2	1:	20 40	.8	113	36.8	1	04	36.5	10	7 33.8	5	111	
		OE	A	-40°C to 85°C	24.1	237	22.1	2	29 21	.4	230	21.3	2	32	21.7	23	5 22.7	,	244	
+	Enable time	0E	A	-40°C to 125°C	34.9	156	33.3	1	67 32	.0	169	31.7	1	73	32.0	17	7 34.2	2	187	ns
t _{en}		OE	в	-40°C to 85°C	21.3	237	14.3	1	52 11	.2	140	8.8	1	30	8.2	13	0 8.4		132	115
				-40°C to 125°C	29.8	143	23.0	1	6 18	.6	107	15.4		97	14.5	ç	7 14.8	6	103	



7.8 Switching Characteristics, $V_{CCA} = 1.5 \pm 0.1 V$

										В	-Port S	Supply	Voltag	e (V _{CC}	в)							
I	PARAMETER	FROM	то	Test Conditions	1.2	± 0.1 V	1.	5 ± 0.1	V	1.8	3 ± 0.15	5 V	2.	5 ± 0.2	v	3.	3 ± 0.3	v	5.	0 ± 0.5	V	UNIT
					MIN	ΤΥΡ ΜΑΧ	MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	MIN	ΤΥΡ	MAX	
		A	В	-40°C to 85°C	1.9	80	0.5		31	0.5		25	0.5		19	0.5		17	0.5		15	
+ .	Propagation	^		-40°C to 125°C	4.1	51	1.6		31	0.5		25	0.5		20	0.5		18	0.5		16	ns
t _{pd}	delay	В	A	-40°C to 85°C	0.5	43	0.5		31	0.5		28	0.5		26	0.5		25	0.5		24	
		Б	A	-40°C to 125°C	3.0	39	1.6		31	0.5		28	0.5		26	0.5		25	0.5		24	
		OE	A	-40°C to 85°C	20.0	91	19.0		82	18.8		81	19.2		82	19.6		83	12.2		87	
+	Disable time	OL		-40°C to 125°C	34.9	95	32.6		86	32.8		85	33.4		87	34.2		88	24.6		92	ns
t _{dis}		OE	В	-40°C to 85°C	27.4	127	21.7		91	19.9		82	16.3		71	15.9		71	13.7		70	115
		UE	D	-40°C to 125°C	44.4	130	36.7		95	34.7		86	30.2		75	29.8		75	26.6		74	
		OE	A	-40°C to 85°C	14.9	102	14.4		86	13.5		88	12.7		90	12.6		92	13.2		97	
	Enable time	UE	A	-40°C to 125°C	25.5	102	25.2		89	24.1		91	22.8		93	22.8		96	23.5		100	
t _{en}		OE	в	-40°C to 85°C	17.9	175	12.7		80	9.1		69	6.1		57	4.9		53	4.5		54	ns
		OL		-40°C to 125°C	26.6	135	21.0		81	16.8		71	12.5		60	10.8		56	10.4		57	



7.9 Switching Characteristics, V_{CCA} = 1.8 ± 0.15 V

				_					В	-Port S	upply	Voltag	je (V _{CCE}	3)							
	PARAMETER	FROM	то	Test Conditions	1.2 ± 0.1	V	1.5 ±	0.1 V	1.8	3 ± 0.15	V	2.	5 ± 0.2	v	3.	3 ± 0.3 V	/	5.	0 ± 0.5	V	UNIT
					MIN TYP	MAX	MIN T	P MAX	MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP I	MAX	MIN	TYP	MAX	
		А	в	-40°C to 85°C	0.5	75	0.5	28	0.5		22	0.5		17	0.5		14	0.5		12	
+ .	Propagation	^	D	-40°C to 125°C	2.9	48	0.5	28	0.5		23	0.5		17	0.5		15	0.5		13	ns
t _{pd}	delay	В	A	-40°C to 85°C	0.5	37	0.5	25	0.5		22	0.5		19	0.5		19	0.5		18	115
		Б	A	-40°C to 125°C	1.4	33	0.5	25	0.5		23	0.5		20	0.5		19	0.5		19	
		OE	A	-40°C to 85°C	17.2	79	14.7	67	14.5		65	14.3		65	14.4		66	8.5		68	
+	Disable time	OL		-40°C to 125°C	30.9	83	28.0	71	26.6		69	27.5		70	27.2		71	20.0		73	ns
t _{dis}		OE	В	-40°C to 85°C	25.4	121	18.7	81	16.5		71	12.8		60	12.5		58	9.8		55	115
		0E	D	-40°C to 125°C	41.7	123	34.0	86	30.3		76	26.2		64	25.3		62	21.8		59	
		OE	A	-40°C to 85°C	10.9	88	9.5	66	9.4		63	8.6		65	8.2		66	8.1		69	
+	Enable time	0E	A	-40°C to 125°C	20.3	87	19.0	69	18.9		67	17.6		68	17.1		70	17.1		73	
t _{en}		OE	в	-40°C to 85°C	16.7	177	10.4	75	8.1		58	4.9		46	3.3		42	2.2		39	ns
				-40°C to 125°C	25.1	135	18.7	77	15.5		60	11.0		49	8.7		44	7.3		42	



7.10 Switching Characteristics, $V_{CCA} = 2.5 \pm 0.2 V$

	<u> </u>			_	<u> </u>	<u> </u>				В	-Port S	Supply	Voltag	e (V _{CC}	в)							
I	PARAMETER	FROM	то	Test Conditions	1.2 ± (0.1 V	1.	5 ± 0.1	v	1.8	3 ± 0.15	5 V	2.	5 ± 0.2	V	3.	3 ± 0.3	v	5.	0 ± 0.5	V	UNIT
					MIN TY	P MAX	MIN	ТҮР	MAX	MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	
		A	в	-40°C to 85°C	0.5	70	0.5		26	0.5		20	0.5		14	0.5		12	0.5		9	
	Propagation			-40°C to 125°C	1.8	45	0.5		26	0.5		20	0.5		14	0.5		12	0.5		10	na
t _{pd}	delay	В	A	-40°C to 85°C	0.5	32	0.5		19	0.5		17	0.5		14	0.5		13	0.5		13	ns
		Б	A	-40°C to 125°C	0.5	28	0.5		20	0.5		17	0.5		14	0.5		13	0.5		13	
		OE	A	-40°C to 85°C	12.9	65	10.5		51	9.0		51	8.1		43	8.4		44	5.0		45	
•	Disable time	OL		-40°C to 125°C	24.9	68	21.8		55	19.7		50	18.2		47	18.6		48	15.0		49	ns
t _{dis}		OE	В	-40°C to 85°C	23.2	112	16.5		74	14.0		61	9.0		46	9.1		44	6.4		39	115
		UE	D	-40°C to 125°C	38.7	115	30.9		79	27.1		66	21.6		51	20.5		48	16.8		43	
		OE	A	-40°C to 85°C	7.9	80	5.9		50	5.1		44	4.7		39	4.4		40	3.7		41	
	Enable time	UE	A	-40°C to 125°C	15.6	74	13.5		53	12.4		47	12.0		42	11.5		43	10.8		44	
t _{en}		OE	в	-40°C to 85°C	16.3	183	9.2		74	6.0		54	4.0		36	2.1		31	0.5		27	ns
		OL		-40°C to 125°C	24.4	139	17.2		76	13.0		57	9.8		38	7.1		33	4.7		29	



7.11 Switching Characteristics, $V_{CCA} = 3.3 \pm 0.3 V$

										B	-Port S	Supply	Voltag	je (V _{CCI}	з)							
	PARAMETER	FROM	то	Test Conditions	1.2 ± 0.1	1 V	1.	5 ± 0.1 V	/	1.8	3 ± 0.15	5 V	2.	.5 ± 0.2	V	3.	.3 ± 0.3	v	5.	0 ± 0.5	V	UNIT
					MIN TYP	MAX	MIN	TYP I	MAX	MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	
		А	в	-40°C to 85°C	0.5	69	0.5		25	0.5		19	0.5		13	0.5		11	0.5		8	
+	Propagation	^		-40°C to 125°C	1.5	44	0.5		25	0.5		19	0.5		13	0.5		11	0.5		9	ns
t _{pd}	delay	В	A	-40°C to 85°C	0.5	30	0.5		17	0.5		14	0.5		12	0.5		11	0.5		10	115
		В		-40°C to 125°C	0.5	27	0.5		18	0.5		15	0.5		12	0.5		11	0.5		10	
		OE	A	-40°C to 85°C	12.9	62	10.1		47	8.7		42	6.9		39	6.6		39	6.9		40	
+	Disable time	OL		-40°C to 125°C	24.0	65	20.6		51	18.4		46	15.7		40	15.3		39	15.9		40	ns
t _{dis}	Disable time	OE	в	-40°C to 85°C	22.7	109	15.7		71	13.2		59	8.5		42	7.6		38	4.7		34	115
		UE	D	-40°C to 125°C	37.6	111	29.5		75	25.4		63	19.2		46	18.5		42	14.2		36	
		OE	A	-40°C to 85°C	6.6	85	4.2		45	3.0		37	2.4		31	2.2		30	1.7		30	
+	Enable time	UE		-40°C to 125°C	13.6	72	10.9		47	9.3		40	8.2		33	8.1		32	7.5		33	nc
t _{en}		OE	в	-40°C to 85°C	16.3	192	8.9		76	5.4		55	2.6		34	1.8		27	0.5		22	ns
		UL		-40°C to 125°C	24.3	144	16.7		78	12.2		57	8.0		36	6.6		29	3.7		24	



7.12 Switching Characteristics, $V_{CCA} = 5.0 \pm 0.5 V$

	<u> </u>			_		,				B	-Port S	upply	Voltag	e (V _{CC}	в)							
I	PARAMETER	FROM	то	Test Conditions	1.2 ± 0	.1 V	1.8	5 ± 0.1 V	V	1.8	3 ± 0.15	V	2.	5 ± 0.2	V	3.	3 ± 0.3 \	v	5.	0 ± 0.5	V	UNIT
					MIN TYP	MAX	MIN	TYP I	MAX	MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	
		A	в	-40°C to 85°C	0.5	69	0.5		24	0.5		18	0.5		13	0.5		10	0.5		8	
	Propagation			-40°C to 125°C	1.3	44	0.5		24	0.5		19	0.5		13	0.5		11	0.5		8	n 0
t _{pd}	delay	В	A	-40°C to 85°C	0.5	31	0.5		15	0.5		12	0.5		9	0.5		8	0.5		8	ns
		Б	A	-40°C to 125°C	0.5	26	0.5		16	0.5		13	0.5		10	0.5		9	0.5		8	
		OE	A	-40°C to 85°C	10.8	58	7.7		42	5.9		36	4.2		31	3.4		30	2.8		26	
+	Disable time	OL		-40°C to 125°C	20.8	61	17.0		46	14.5		40	11.8		33	10.4		31	9.6		29	ns
t _{dis}		OE	В	-40°C to 85°C	9.7	109	5.9		69	13.2		56	8.4		40	6.9		36	3.7		29	115
		UE	D	-40°C to 125°C	37.4	111	29.2		73	24.6		60	18.1		43	16.4		39	12.2		31	
		OE	A	-40°C to 85°C	6.0	102	2.8		44	1.2		33	0.5		25	0.5		22	0.5		21	
	Enable time	UE	A	-40°C to 125°C	12.4	81	8.8		46	6.5		36	4.7		27	4.2		24	4.4		23	n 0
t _{en}		OE	в	-40°C to 85°C	16.7	212	8.8		82	4.8		58	1.6		35	0.5		26	0.5		19	ns
		0L		-40°C to 125°C	24.8	158	16.7		83	11.7		60	6.9		37	4.7		28	3.5		21	



7.13 Operating Characteristics

T _A =	25℃	(1)
------------------	-----	-----

				Su	pply Voltage	(V _{CCB} = V _{CC}	;A)		
	PARAMETER	Test Conditions	1.2 ± 0.1V	1.5 ± 0.1V	1.8 ± 0.15V	2.5 ± 0.2V	3.3 ± 0.3V	5.0 ± 0.5V	UNIT
			TYP	ТҮР	TYP	TYP	TYP	TYP	
	A to B: outputs enabled	A Port	2	2	2	2	2	3	
C (2)	A to B: outputs disabled	CL = 0, RL = Open	2	2	2	2	2	3	pF
C _{pdA} ⁽²⁾	B to A: outputs enabled	f = 10 MHz	12	12	12	13	13	16	рг
	B to A: outputs disabled	t _{rise} = t _{fall} = 1 ns	2	2	2	2	2	3]
	A to B: outputs enabled	B Port	12	12	12	13	13	16	
C (3)	A to B: outputs disabled	CL = 0, RL = Open	2	2	2	2	2	3	pF
C _{pdB} ⁽³⁾	B to A: outputs enabled	f = 10 MHz	2	2	2	2	2	3	PL
	B to A: outputs disabled	t _{rise} = t _{fall} = 1 ns	2	2	2	2	2	3	

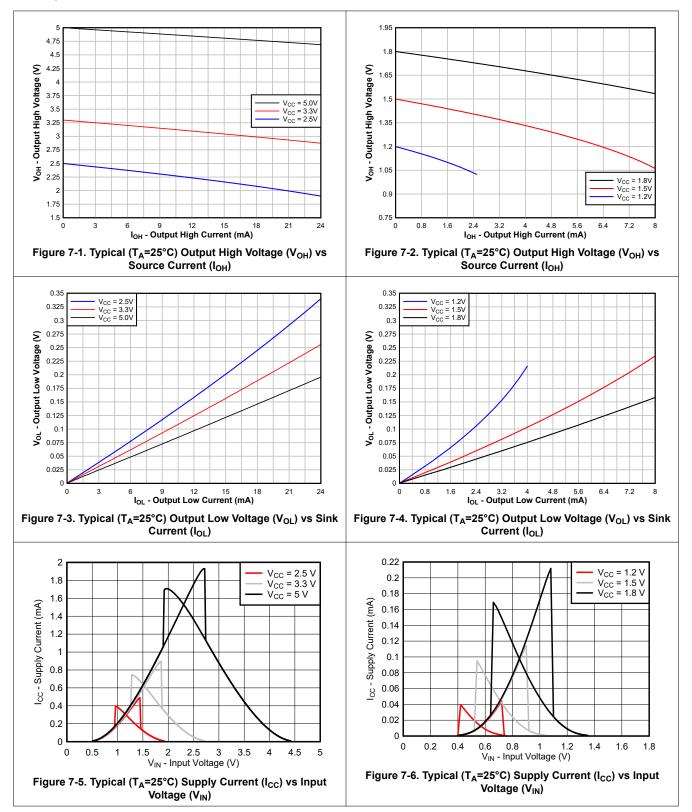
 See the CMOS Power Consumption and C_{pd} Calculation application report for additional information about how power dissipation capacitance affects power consumption.

(2) A-Port power dissipation capacitance per transceiver.

(3) B-Port power dissipation capacitance per transceiver.



7.14 Typical Characteristics



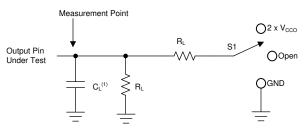


8 Parameter Measurement Information

8.1 Load Circuit and Voltage Waveforms

Unless otherwise noted, generators supply all input pulses that have the following characteristics:

- f = 1 MHz
- Z_O = 50 Ω
- Δt/ΔV ≤ 1 ns/V

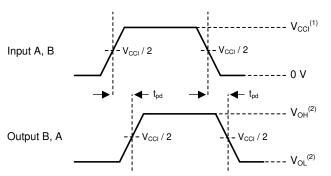


A. C_L includes probe and jig capacitance.

Figure 8-1. Load Circuit

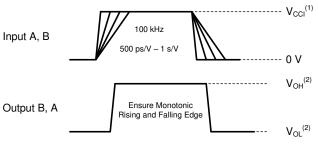
		au circui	Conditions		
Parameter	V _{cco}	RL	CL	S ₁	V _{TP}
t _{pd} Propagation (delay) time	1.1 V – 5.5 V	10 kΩ	5 pF	Open	N/A
	1.1 V – 1.6 V	10 kΩ	5 pF	2 × V _{CCO}	0.1 V
t_{en}, t_{dis} Enable time, disable time	1.65 V – 2.7 V	10 kΩ	5 pF	2 × V _{CCO}	0.15 V
	3.0 V – 5.5 V	10 kΩ	5 pF	2 × V _{CCO}	0.3 V
	1.1 V – 1.6 V	10 kΩ	5 pF	GND	0.1 V
t_{en} , t_{dis} Enable time, disable time	1.65 V – 2.7 V	10 kΩ	5 pF	GND	0.15 V
	3.0 V – 5.5 V	10 kΩ	5 pF	GND	0.3 V





- 1. V_{CCI} is the supply pin associated with the input port.
- 2. V_{OH} and V_{OL} are typical output voltage levels that occur with specified R_L , C_L , and S_1

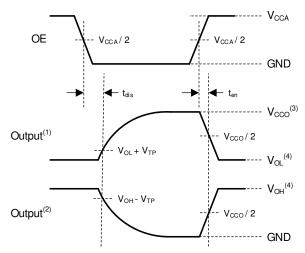
Figure 8-2. Propagation Delay



- 1. V_{CCI} is the supply pin associated with the input port.
- 2. V_{OH} and V_{OL} are typical output voltage levels that occur with specified R_L , C_L , and S_1

Figure 8-3. Input Transition Rise and Fall Rate





- A. 1. Output waveform on the condition that input is driven to a valid Logic Low.
 - 2. Output waveform on the condition that input is driven to a valid Logic High.
 - 3. V_{CCO} is the supply pin associated with the output port.
 - 4. $V_{OH} \mbox{ and } V_{OL} \mbox{ are typical output voltage levels with specified R_L, C_L, and S_1.}$

Figure 8-4. Enable Time And Disable Time



9 Detailed Description

9.1 Overview

The TXU0104 is a 4-bit translating transceiver that uses two individually configurable power-supply rails. The device is operational with V_{CCA} and V_{CCB} supplies as low as 1.1 V and as high as 5.5 V. Additionally, the device can be operated with $V_{CCA} = V_{CCB}$. The A port is designed to track V_{CCA} , and the B port is designed to track V_{CCB} .

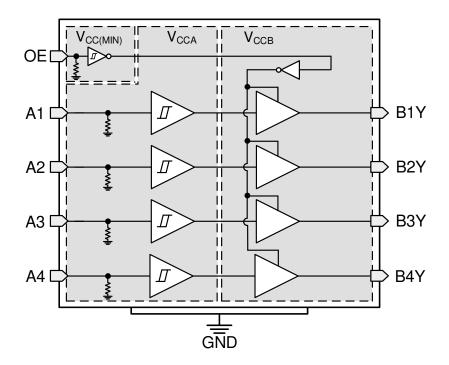
The TXU0104 device is designed for asynchronous communication between data buses, and transmits data with fixed direction from the A bus to the B bus on some channels and from the B bus to the A bus on the remaining channels. The output-enable input (OE) is used to disable the outputs so the buses are effectively isolated. The output-enable pin of the TXU0104 (OE) can be referenced to either V_{CCA} or V_{CCB} . The OE pin can be left floating or externally pulled down to ground to ensure the high-impedance state of the level shifter outputs during power up or power down.

This device is fully specified for partial-power-down applications using the I_{off} current. The I_{off} protection circuitry ensures that no excessive current is drawn from or sourced into an input or output while the device is powered down.

The VCC isolation or VCC disconnect feature ensures that if either VCC is less than 100 mV or disconnected with the complementary supply within recommended operating conditions, outputs are disabled and set to the high-impedance state while the supply current is maintained. The I_{off-float} circuitry ensures that no excessive current is drawn from or sourced into an input or output while the supply is floating.

Glitch-free power supply sequencing allows either supply rail to be powered on or off in any order while providing robust power sequencing performance.

9.2 Functional Block Diagram





9.3 Feature Description

9.3.1 CMOS Schmitt-Trigger Inputs with Integrated Pulldowns

Standard CMOS inputs are high impedance and are typically modeled as a resistor in parallel with the input capacitance given in the *Electrical Characteristics*. The worst case resistance is calculated with the maximum input voltage, given in the *Absolute Maximum Ratings*, and the maximum input leakage current, given in the *Electrical Characteristics*, using ohm's law ($R = V \div I$).

The Schmitt-trigger input architecture provides hysteresis as defined by ΔV_T in the *Electrical Characteristics*, which makes this device extremely tolerant to slow or noisy inputs. Driving the inputs slowly will increase dynamic current consumption of the device. See *Understanding Schmitt Triggers* for additional information regarding Schmitt-trigger inputs.

9.3.1.1 Inputs with Integrated Static Pull-Down Resistors

This device has 5 M Ω typical integrated weak pull-downs for each input. This feature allows all inputs to be left floating without the concern for unstable outputs or increased current consumption. This also helps to reduce external component count for applications where not all channels are used or need to be fixed low. If an external pull-up is required, it should be no larger than 1 M Ω to avoid contention with the 5 M Ω internal pull-down.

9.3.2 Control Logic (OE) with V_{CC(MIN)} Circuitry

The output-enable input (OE) is used to disable the outputs so the buses are effectively isolated. The output-enable pin of the TXU0x04 has $V_{CC(MIN)}$ circuitry, which allows the OE pin to operate with the lower supply voltage. The *Over-Voltage Tolerant Inputs* feature allows the OE pin to operate with the higher supply voltage. This combination means that the enable pin can be referenced to either V_{CCA} or V_{CCB} supply. Multiple permutations of each device are possible since the controller can be placed on either the A or B port and can still control the enable pin.

9.3.3 Balanced High-Drive CMOS Push-Pull Outputs

A balanced output allows the device to sink and source similar currents. The high drive capability of this device creates fast edges into light loads, so routing and load conditions should be considered to prevent ringing. Additionally, the outputs of this device are capable of driving larger currents than the device can sustain without being damaged. *Absolute Maximum Ratings* defines the electrical and thermal limits that must be followed at all times.

9.3.4 Partial Power Down (I_{off})

The inputs and outputs for this device enter a high-impedance state when the device is powered down, inhibiting current backflow into the device. The I_{off} in the *Electrical Characteristics* specifies the maximum leakage into or out of any input or output pin on the device.

9.3.5 VCC Isolation and V_{CC} Disconnect

The outputs for this device are disabled and enter a high-impedance state when either supply is <100 mV or left floating (disconnected), with the complementary supply within recommended operating conditions. It is recommended that the inputs are kept low before floating (disconnecting) either supply.

The I_{CCx(floating)} in the *Electrical Characteristics* specifies the maximum supply current. The I_{off(float)} in the *Electrical Characteristics* specifies the maximum leakage into or out of any input or output pin on the device.



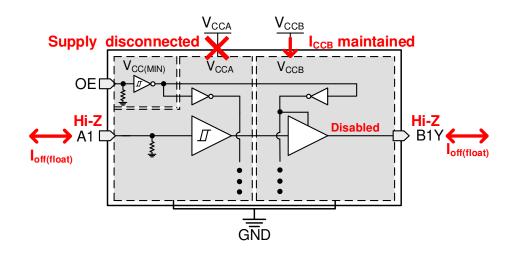


Figure 9-1. V_{CC} Disconnect Feature

9.3.6 Over-Voltage Tolerant Inputs

Input signals to this device can be driven above the supply voltage so long as they remain below the maximum input voltage value specified in the *Recommended Operating Conditions*.

9.3.7 Glitch-Free Power Supply Sequencing

Either supply rail may be powered on or off in any order without producing a glitch on the inputs or outputs (that is, where the output erroneously transitions to VCC when it should be held low or vice versa). Glitches of this nature can be misinterpreted by a peripheral as a valid data bit, which could trigger a false device reset of the peripheral, a false device configuration of the peripheral, or even a false data initialization by the peripheral.



9.3.8 Negative Clamping Diodes

Figure 9-2 depicts the inputs and outputs to this device that have negative clamping diodes.

CAUTION

Voltages beyond the values specified in the *Absoulte Maximum Ratings* table can cause damage to the device. The input negative-voltage and output voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

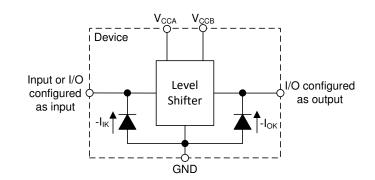


Figure 9-2. Electrical Placement of Clamping Diodes for Each Input and Output

9.3.9 Fully Configurable Dual-Rail Design

The V_{CCA} and V_{CCB} pins can be supplied at any voltage from 1.1 V to 5.5 V, making the device suitable for translating between any of the voltage nodes (1.2 V, 1.5 V, 1.8 V, 3.3 V, and 5.0 V).

9.3.10 Supports High-Speed Translation

The TXU0104 device can support high data-rate applications. The translated signal data rate can be up to 200 Mbps when the signal is translated from 3.3 V to 5.0 V.

9.4 Device Functional Modes

CONTROL INPUTS	Port St	tatus	OPERATION
OE	Input	Output	OFERATION
Н	L	L	Unidirectional non-inverting voltage translation
Н	Н	Н	Unidirectional non-inverting voltage translation
L	Х	Hi-Z	Isolation

Table 9-1. Function Table



10 Application and Implementation

Note

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes, as well as validating and testing their design implementation to confirm system functionality.

10.1 Application Information

The TXU0104 device can be used in level-translation applications for interfacing devices or systems operating at different interface voltages with one another. The TXU0104 device is ideal for use in applications where a push-pull driver is connected to the data Inputs. The max data rate can be up to 200 Mbps when device translates a signal from 3.3 V to 5.0 V.

10.2 Typical Application

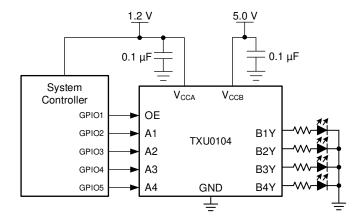


Figure 10-1. TXU0104 LED Driver Application

10.2.1 Design Requirements

Use the parameters listed in Table 10-1 for this design example.

Table 10-1. Design Parameters

DESIGN PARAMETERS	EXAMPLE VALUES
Input voltage range	1.1 V to 5.5 V
Output voltage range	1.1 V to 5.5 V

10.2.2 Detailed Design Procedure

To begin the design process, determine the following:

- Input voltage range
 - Use the supply voltage of the device that is driving the TXU0104 device to determine the input voltage range. For a valid logic-high, the value must exceed the positive-going input-threshold voltage (V_{T+}) of the input port. For a valid logic low the value must be less than the negative-going input-threshold voltage (V_{T-}) of the input port.
- Output voltage range
 - Use the supply voltage of the device that the TXU0104 device is driving to determine the output voltage range.



10.2.3 Application Curve

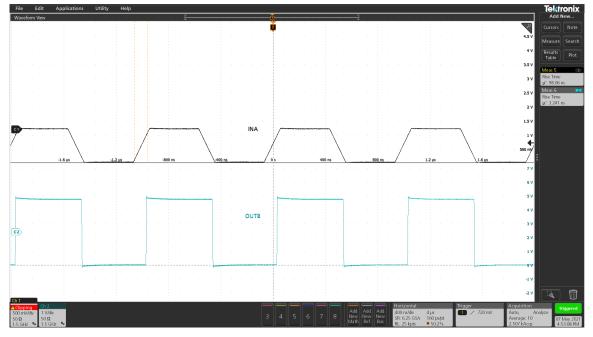


Figure 10-2. Up Translation at 1 MHz (1.2 V to 5 V)

11 Power Supply Recommendations

Always apply a ground reference to the GND pins first. This device is designed for glitch free power sequencing without any supply sequencing requirements such as ramp order or ramp rate.

Glitch-Free Power Supply Sequencing describes how this device was designed with various power supply sequencing methods in mind to help prevent unintended triggering of downstream devices.

12 Layout

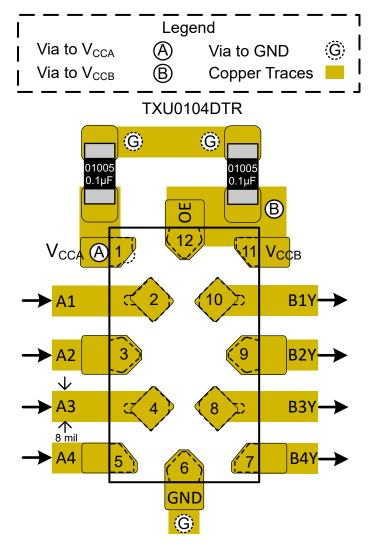
12.1 Layout Guidelines

To ensure reliability of the device, following common printed-circuit board layout guidelines are recommended:

- Use bypass capacitors on the power supply pins and place them as close to the device as possible. A 0.1 μF capacitor is recommended, but transient performance can be improved by having 1 μF and 0.1 μF capacitors in parallel as bypass capacitors.
- The high drive capability of this device creates fast edges into light loads so routing and load conditions should be considered to prevent ringing.



12.2 Layout Example







13 Device and Documentation Support

13.1 Device Support

13.1.1 Regulatory Requirements

No statutory or regulatory requirements apply to this device.

There are no special characteristics for this product.

13.2 Documentation Support

13.2.1 Related Documentation

- Texas Instruments, Understanding Schmitt Triggers application report
- Texas Instruments, CMOS Power Consumption and Cpd Calculation application report

13.3 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. Click on *Subscribe to updates* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

13.4 Support Resources

TI E2E[™] support forums are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

Linked content is provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's Terms of Use.

13.5 Trademarks

TI E2E[™] is a trademark of Texas Instruments.

All trademarks are the property of their respective owners.

13.6 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

13.7 Glossary

TI Glossary This glossary lists and explains terms, acronyms, and definitions.

14 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.



PACKAGING INFORMATION

Orderable Device	Status	Package Type		Pins	-	Eco Plan	Lead finish/	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	Ball material	(3)		(4/5)	
TYLIOLOAD	ACTIVE	WQFN	BQA	1.1	2000	RoHS & Green	()		40 to 125	TX0104	
TXU0104BQAR	ACTIVE	WQFN	BQA	14	3000	ROHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	TX0104	Samples
TXU0104DTRR	ACTIVE	X2QFN	DTR	12	3000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	1KJ	Samalar
											Samples
TXU0104PWR	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	TXU0104	Samples
TXU0104RUTR	ACTIVE	UQFN	RUT	12	3000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	1J4	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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PACKAGE OPTION ADDENDUM

continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF TXU0104 :

• Automotive : TXU0104-Q1

NOTE: Qualified Version Definitions:

• Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects



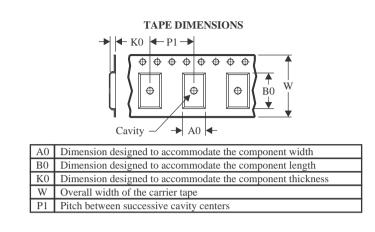
Texas

*All dimensions are nominal

STRUMENTS

TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



Device		Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TXU0104BQAR	WQFN	BQA	14	3000	180.0	12.4	2.8	3.3	1.1	4.0	12.0	Q1
TXU0104DTRR	X2QFN	DTR	12	3000	180.0	9.5	0.93	1.49	0.43	2.0	8.0	Q1
TXU0104PWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
TXU0104RUTR	UQFN	RUT	12	3000	180.0	9.5	1.9	2.2	0.7	4.0	8.0	Q1



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PACKAGE MATERIALS INFORMATION

3-Jun-2022



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TXU0104BQAR	WQFN	BQA	14	3000	210.0	185.0	35.0
TXU0104DTRR	X2QFN	DTR	12	3000	189.0	185.0	36.0
TXU0104PWR	TSSOP	PW	14	2000	356.0	356.0	35.0
TXU0104RUTR	UQFN	RUT	12	3000	189.0	185.0	36.0

PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE



A. An integration of the information o

Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.

Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.

E. Falls within JEDEC MO-153





NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

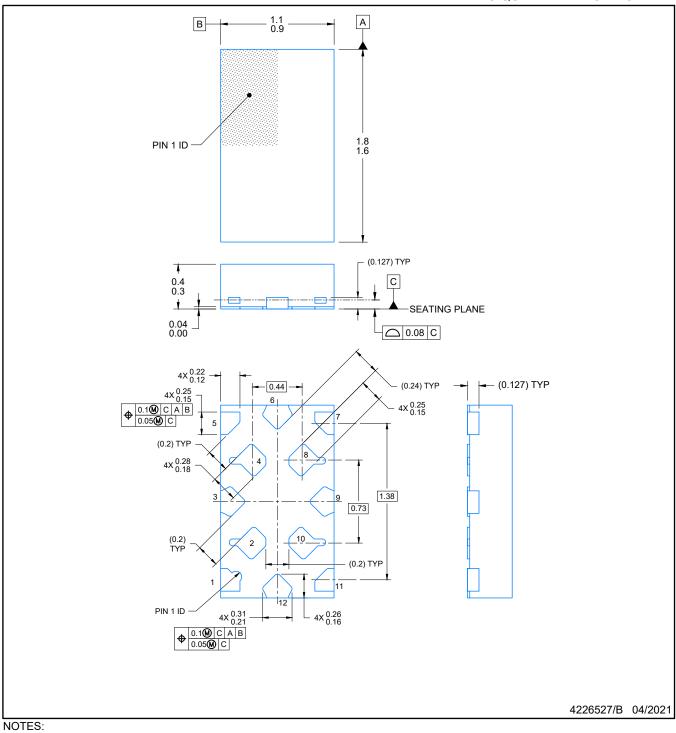


DTR0012A

PACKAGE OUTLINE

X2QFN - 0.4 mm max height

PLASTIC QUAD FLATPACK-NO LEAD



- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.

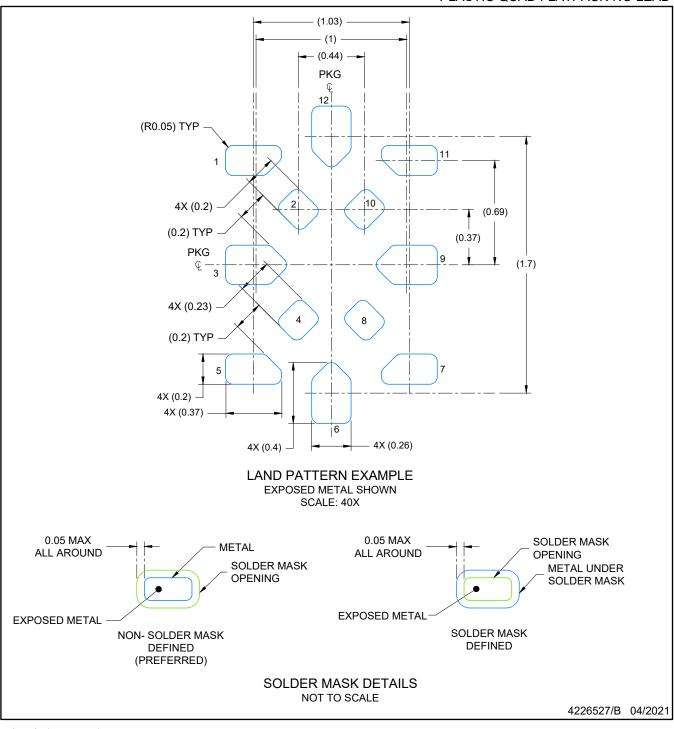


DTR0012A

EXAMPLE BOARD LAYOUT

X2QFN - 0.4 mm max height

PLASTIC QUAD FLATPACK-NO LEAD



NOTES: (continued)

- 3. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271).
- 4. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

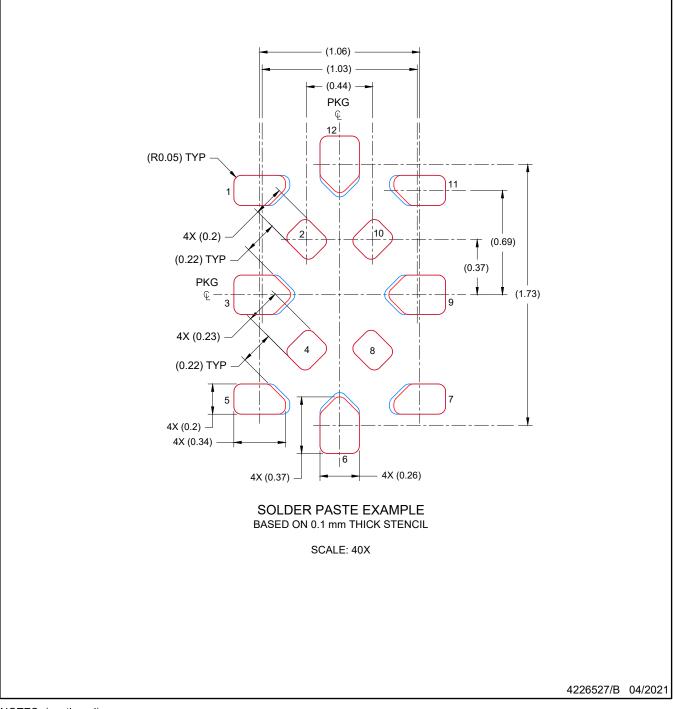


DTR0012A

EXAMPLE STENCIL DESIGN

X2QFN - 0.4 mm max height

PLASTIC QUAD FLATPACK-NO LEAD

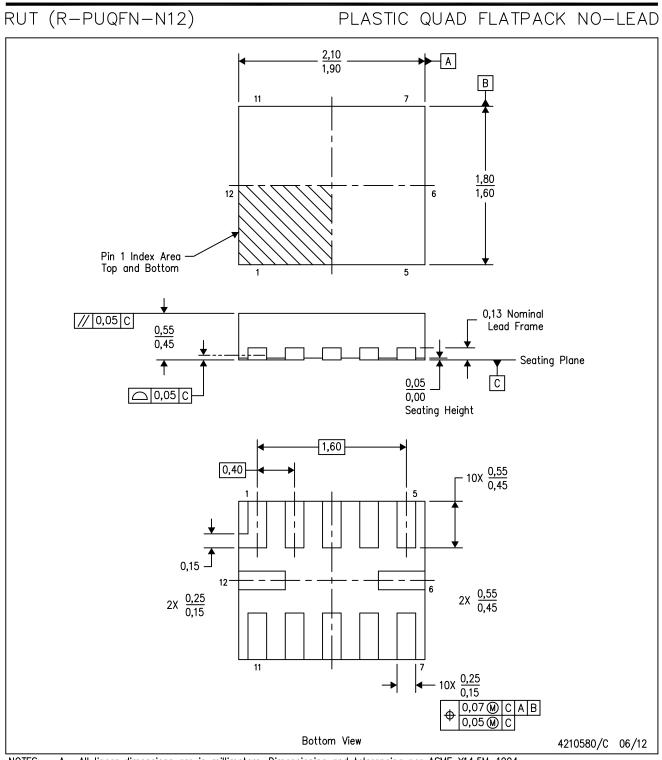


NOTES: (continued)

5. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.



MECHANICAL DATA



NOTES: All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994. Α.

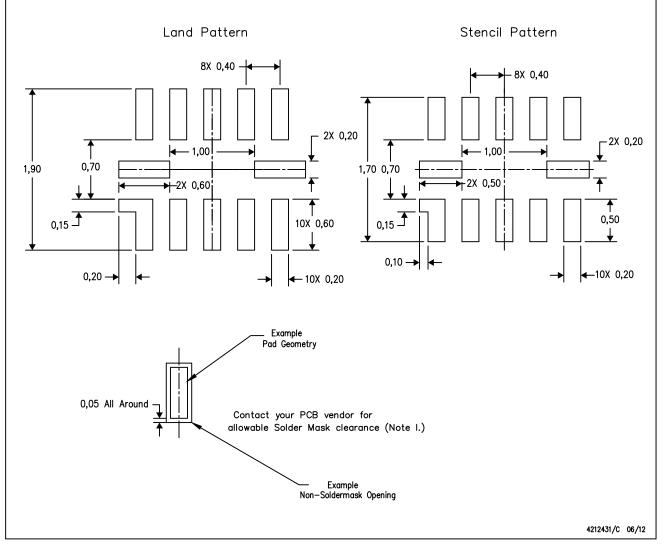
This drawing is subject to change without notice. QFN (Quad Flatpack No-Lead) package configuration. Β.

C.



LAND PATTERN DATA





NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Customers should contact their board fabrication site for minimum solder mask web tolerances between signal pads.
- E. Maximum stencil thickness 0,1016 mm (4 mils). All linear dimensions are in millimeters.
- F. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC 7525 for stencil design considerations.
- G. Over-printing land for larger area ratio is not advised due to land width and bridging potential. Exersize extreme caution.
- H. Suggest stencils cut with lasers such as Fiber Laser that produce the greatest positional accuracy.
- I. Component placement force should be minimized to prevent excessive paste block deformation.



BQA 14

2.5 x 3, 0.5 mm pitch

GENERIC PACKAGE VIEW

WQFN - 0.8 mm max height

PLASTIC QUAD FLATPACK - NO LEAD

This image is a representation of the package family, actual package may vary. Refer to the product data sheet for package details.





BQA0014A

PACKAGE OUTLINE

WQFN - 0.8 mm max height

PLASTIC QUAD FLAT PACK-NO LEAD



NOTES:

- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.
- 3. The package thermal pad must be soldered to the printed circuit board for optimal thermal and mechanical performance.



BQA0014A

EXAMPLE BOARD LAYOUT

WQFN - 0.8 mm max height

PLASTIC QUAD FLAT PACK-NO LEAD



NOTES: (continued)

- 4. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271).
- 5. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.



BQA0014A

EXAMPLE STENCIL DESIGN

WQFN - 0.8 mm max height

PLASTIC QUAD FLAT PACK-NO LEAD



NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.



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